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June 2015

FDZ1416NZ

Common Drain N-Channel 2.5 V PowerTrench® WL-CSP MOSFET

24 V, 7 A, 23 mΩ

Features

- Max $r_{S1S2(on)} = 23 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_{S1S2} = 1 \text{ A}$
- Max $r_{S1S2(on)} = 25 \text{ m}\Omega$ at $V_{GS} = 4 \text{ V}$, $I_{S1S2} = 1 \text{ A}$
- Max $r_{S1S2(on)} = 28 \text{ m}\Omega$ at $V_{GS} = 3.1 \text{ V}$, $I_{S1S2} = 1 \text{ A}$
- Max $r_{S1S2(on)} = 33 \text{ m}\Omega$ at $V_{GS} = 2.5 \text{ V}$, $I_{S1S2} = 1 \text{ A}$
- Occupies only 2.2 mm² of PCB area
- Ultra-thin package: less than 0.35 mm height when mounted to PCB
- High power and current handling capability
- HBM ESD protection level > 3.2 kV (Note 3)
- RoHS Compliant

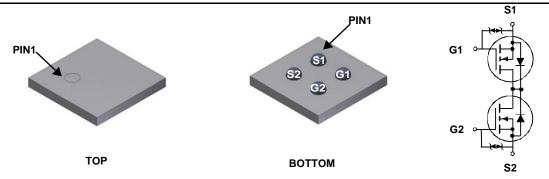


General Description

This device is designed specifically as a single package solution for Li-lon battery pack protection circuit and other ultra-portable applications. It features two common drain N-channel MOSFETs, which enables bidirectional current flow, on Fairchild's advanced PowerTrench® process with state of the art "low pitch" WLCSP packaging process, the FDZ1416NZ minimizes both PCB space and $r_{\rm S1S2(on)}.$ This advanced WLCSP MOSFET embodies a breakthrough in packaging technology which enables the device to combine excellent thermal transfer characteristics, ultra-low profile packaging, low gate charge and low $r_{\rm S1S2(on)}.$

Applications

- Battery management
- Load switch
- Battery protection



WL-CSP 1.4X1.6

MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter			Ratings	Units	
V _{S1S2}	Source1 to Source2 Voltage			24	V	
V _{GS}	Gate to Source Voltage			±12	V	
1	Source1 to Source2 Current -Continuous	T _A = 25°C	(Note 1a)	7		
I _{S1S2}	-Pulsed			30	A	
D	Power Dissipation	T _A = 25°C	(Note 1a)	1.7	10/	
P_{D}	Power Dissipation	T _A = 25°C	(Note 1b)	0.5	W	
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	74	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	230	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
EN	FDZ1416NZ	WL-CSP 1.4X1.6	7 "	8 mm	5000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Characteristics						
I _{S1S2}	Zero Gate Voltage Source1 to Source2 Current	V _{S1S2} = 19 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±12 V, V _{S1S2} = 0 V			±10	μΑ

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{S1S2}, I_{S1S2} = 250 \mu A$	0.4	0.9	1.3	V
		V _{GS} = 4.5 V, I _{S1S2} = 1 A	9	16	23	
		V _{GS} = 4 V, I _{S1S2} = 1 A	10	17	25	
r _{S1S2(on)}	Static Source1 to Source2 On Resistance	V _{GS} = 3.1 V, I _{S1S2} = 1 A	11	19	28	mΩ
		V _{GS} = 2.5 V, I _{S1S2} = 1 A	12	22	33	
		V _{GS} = 4.5 V, I _{S1S2} = 1 A,T _J = 125 °C		24	36	
g _{FS}	Forward Transconductance	V _{S1S2} = 5 V, I _{S1S2} = 1 A		4.5		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 42.V. V 0.V	1140	1515	pF
C _{oss}	Output Capacitance	V _{S1S2} = 12 V, V _{GS} = 0 V, f = 1 MHz	136	220	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	129	205	pF

Switching Characteristics

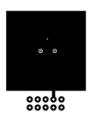
t _{d(on)}	Turn-On Delay Time		9.5	19	ns
t _r	Rise Time	V _{S1S2} = 12 V, I _{S1S2} = 1 A,	12	22	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$	37	59	ns
t _f	Fall Time		16	33	ns
Q_q	Total Gate Charge		12	17	nC
Q_{gs}	Gate to Source1 Gate Charge	$V_{S1S2} = 12 \text{ V, } I_{S1S2} = 1 \text{ A,}$ $V_{G1S1} = 4.5 \text{ V, } V_{G2S2} = 0 \text{ V}$	1.6		nC
Q_{gd}	Gate to Source2 "Miller" Charge	VG1S1 = 4.5 V, VG2S2 = 0 V	3.7		nC

Source1 to Source2 Diode Characteristics

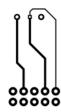
I _{fss}	Maximum Continuous Source1 to Source2 Diode Forward Current				1	Α
V _{fss}	Source1 to Source2 Diode Forward Voltage	$V_{G1S1} = 0 \text{ V, } V_{G2}$ $I_{fss} = 1 \text{ A}$	S2 = 4.5 V, (Note 2)	0.7	1.2	V

Notes

1. R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 74 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 230 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 us, Duty cycle < 2.0%.
- 3. The diode connected between the gate and source serves only protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics T_J = 25°C unless otherwise noted

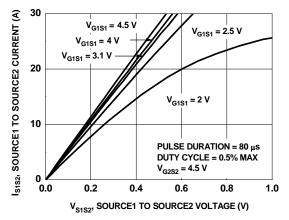


Figure 1. On-Region Characteristics

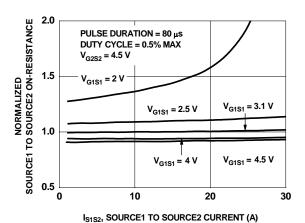


Figure 3. Normalized On-Resistance vs Source1 to Source2 Current and Gate Voltage

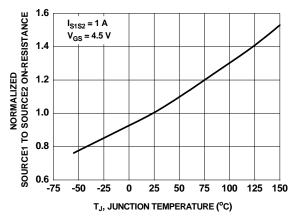
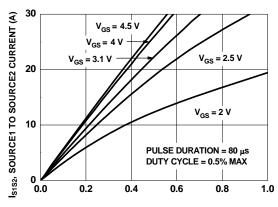


Figure 5. Normalized On Resistance vs Junction Temperature



V_{S1S2}, SOURCE1 TO SOURCE2 VOLTAGE (V)

Figure 2. On-Region Characteristics

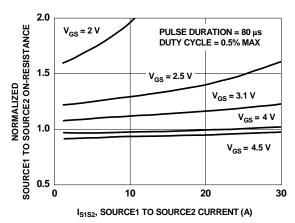


Figure 4. Normalized On-Resistance vs Source1 to Source2 Current and Gate Voltage

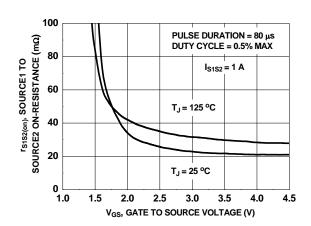


Figure 6. On Resistance vs Gate to Source Voltage

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

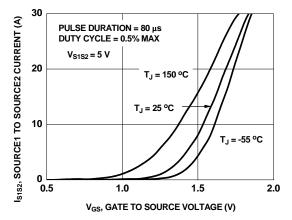


Figure 7. Transfer Characteristics

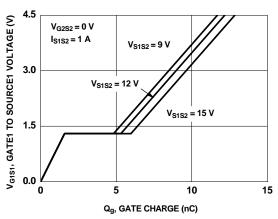


Figure 9. Gate Charge Characteristics

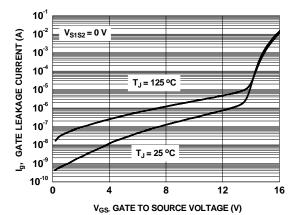
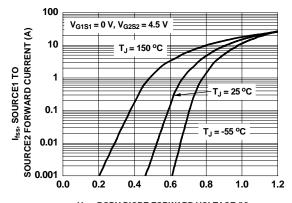


Figure 11. Gate Leakage Current vs Gate to Source Voltage



V_{fss}, BODY DIODE FORWARD VOLTAGE (V)

Figure 8. Source1 to Source2 Diode Forward Voltage vs Source Current

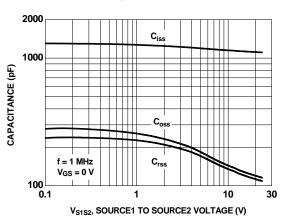
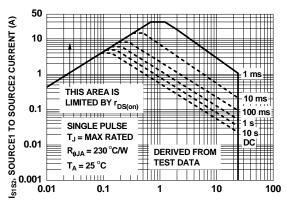


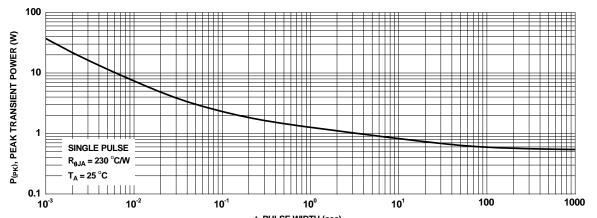
Figure 10. Capacitance vs Source1 to Source2 Voltage



V_{S1S2}, SOURCE1 TO SOURCE2 VOLTAGE (V)

Figure 12. Forward Bias Safe Operating Area

Typical Characteristics T_J = 25°C unless otherwise noted



t, PULSE WIDTH (sec)
Figure 13. Single Pulse Maximum Power Dissipation

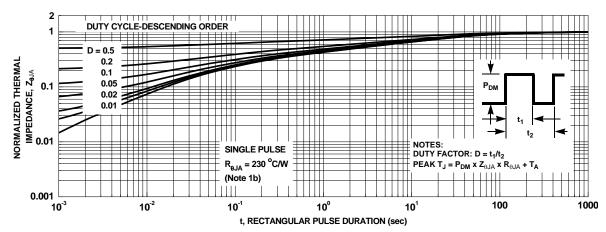


Figure 14. Junction-to-Ambient Transient Thermal Response Curve

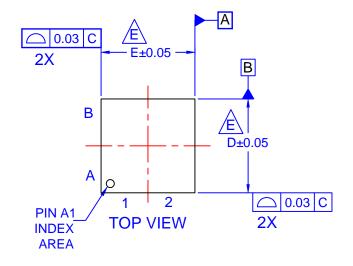
The following information applies to the WL-CSP package dimensions on the next page:

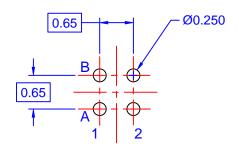
Pin Definitions:

Pin Name	G1	G2	S1	S2
Position	A2	B2	A1	B1

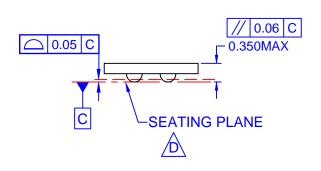
Product Specific Dimensions:

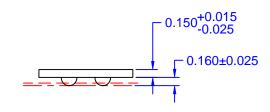
D	E	X	Υ
1.4 mm	1.6 mm	0.475 mm	0.375 mm





LAND PATTERN RECOMMENDATION





NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE

PER ASME Y14.5M, 1994.

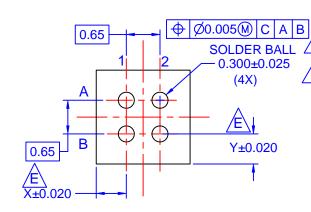
DATUM C IS DEFINED BY THE SPHERICAL

CROWNS OF THE BALLS.

FOR DIMENSIONS D,E,X AND Y SEE

PRODUCT DATA SHEET.

- F. FOR PIN-OUT ASSIGNMENT, REFER TO DATA SHEET.
- G. DRAWING NAME: MKT-UC004AJREV2.



BOTTOM VIEW

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